Reference Only

CHIP COIL (CHIP INDUCTORS) LQP02TQ□□□□02□ Reference Specification

1.Scope

This reference specification applies to LQP02TQ series, Chip coil (Chip Inductors).

2.Part Numbering

(ex) LQ | P | 02 | T | Q | 0N2 | B | 0 | 2 | D

Product ID	Structure	Dimension (L×W)	Applications and Characteristics	Category	Inductance	Tolerance	Features	Electrode	Packaging
								L:4mm-wide / plastic tape D:8mm-wide / paper tape *B:Bulk	

*Bulk packing also available. (A product is put in the plastic bag under the taping conditions.)

3.Rating

・Operating Temperature. –55°C to +125°C
・Storage Temperature. –55°C to +125°C

Customer Part Number	MURATA Part Number	Inductance (nH)	Inductance Tolerance	Q (min)	DC Resistance (Ω max)	Self Resonant Frequency (GHz) *Typ.	Self Resonant Frequency (GHz) Min.	Rated Current (mA)
	LQP02TQ0N2B02D	0.2	B:±0.1nH C:±0.2nH	–	0.1	>20	16.6	990
	LQP02TQ0N2B02L							
	LQP02TQ0N2C02D							
	LQP02TQ0N2C02L							
	LQP02TQ0N3B02D	0.3						
	LQP02TQ0N3B02L							
	LQP02TQ0N3C02D							
	LQP02TQ0N3C02L							
	LQP02TQ0N4B02D	0.4		10				
	LQP02TQ0N4B02L							
	LQP02TQ0N4C02D							
	LQP02TQ0N4C02L							
	LQP02TQ0N5B02D	0.5						730
	LQP02TQ0N5B02L							
	LQP02TQ0N5C02D							
	LQP02TQ0N5C02L							
	LQP02TQ0N6B02D	0.6						
	LQP02TQ0N6B02L							
	LQP02TQ0N6C02D							
	LQP02TQ0N6C02L							
	LQP02TQ0N7B02D	0.7			0.15			630
	LQP02TQ0N7B02L							
	LQP02TQ0N7C02D							
	LQP02TQ0N7C02L							
	LQP02TQ0N8B02D	0.8						
	LQP02TQ0N8B02L							
	LQP02TQ0N8C02D							
	LQP02TQ0N8C02L							
	LQP02TQ0N9B02D	0.9						580
	LQP02TQ0N9B02L							
	LQP02TQ0N9C02D							
	LQP02TQ0N9C02L							
	LQP02TQ1N0B02D	1.0						
	LQP02TQ1N0B02L							
	LQP02TQ1N0C02D							
	LQP02TQ1N0C02L							
	LQP02TQ1N1B02D	1.1			0.2			570
	LQP02TQ1N1B02L							
	LQP02TQ1N1C02D							
	LQP02TQ1N1C02L							

Customer Part Number	MURATA Part Number	Inductance		Q (min)	DC Resistance (Ω max)	Self Resonant Frequency (GHz)		Rated Current (mA)
		(nH)	Tolerance			*Typ.	Min.	
	LQP02TQ1N2B02D	1.2	B:±0.1nH C:±0.2nH	10	0.2	19.6	16.6	550
	LQP02TQ1N2B02L							
	LQP02TQ1N2C02D							
	LQP02TQ1N2C02L							
	LQP02TQ1N3B02D	1.3				>20	15.0	400
	LQP02TQ1N3B02L							
	LQP02TQ1N3C02D							
	LQP02TQ1N3C02L							
	LQP02TQ1N4B02D	1.4				19		
	LQP02TQ1N4B02L							
	LQP02TQ1N4C02D							
	LQP02TQ1N4C02L							
	LQP02TQ1N5B02D	1.5				>20		
	LQP02TQ1N5B02L							
	LQP02TQ1N5C02D							
	LQP02TQ1N5C02L							
	LQP02TQ1N6B02D	1.6			0.3	18.9		390
	LQP02TQ1N6B02L							
	LQP02TQ1N6C02D							
	LQP02TQ1N6C02L							
	LQP02TQ1N7B02D	1.7				19.0		380
	LQP02TQ1N7B02L							
	LQP02TQ1N7C02D							
	LQP02TQ1N7C02L							
	LQP02TQ1N8B02D	1.8				17.7		
	LQP02TQ1N8B02L							
	LQP02TQ1N8C02D							
	LQP02TQ1N8C02L							
	LQP02TQ1N9B02D	1.9				16.8	13.0	
	LQP02TQ1N9B02L							
	LQP02TQ1N9C02D							
	LQP02TQ1N9C02L							
	LQP02TQ2N0B02D	2.0				15.4		
	LQP02TQ2N0B02L							
	LQP02TQ2N0C02D							
	LQP02TQ2N0C02L							
	LQP02TQ2N1B02D	2.1				14.6		
	LQP02TQ2N1B02L							
	LQP02TQ2N1C02D							
	LQP02TQ2N1C02L							
	LQP02TQ2N2B02D	2.2				16.3		
	LQP02TQ2N2B02L							
	LQP02TQ2N2C02D							
	LQP02TQ2N2C02L							
	LQP02TQ2N3B02D	2.3			0.4	16.2		370
	LQP02TQ2N3B02L							
	LQP02TQ2N3C02D							
	LQP02TQ2N3C02L							
	LQP02TQ2N4B02D	2.4						
	LQP02TQ2N4B02L							
	LQP02TQ2N4C02D							
	LQP02TQ2N4C02L							

Customer Part Number	MURATA Part Number	Inductance		Q (min)	DC Resistance (Ω max)	Self Resonant Frequency (GHz)		Rated Current (mA)
		(nH)	Tolerance			*Typ.	Min.	
	LQP02TQ2N5B02D	2.5	B:±0.1nH C:±0.2nH	10	0.4	14.9	11.5	370
	LQP02TQ2N5B02L							
	LQP02TQ2N5C02D							
	LQP02TQ2N5C02L							
	LQP02TQ2N6B02D	2.6				14.6		
	LQP02TQ2N6B02L							
	LQP02TQ2N6C02D							
	LQP02TQ2N6C02L							
	LQP02TQ2N7B02D	2.7				13.5		
	LQP02TQ2N7B02L							
	LQP02TQ2N7C02D							
	LQP02TQ2N7C02L							
	LQP02TQ2N8B02D	2.8			0.45	12.8	10.0	360
	LQP02TQ2N8B02L							
	LQP02TQ2N8C02D							
	LQP02TQ2N8C02L							
	LQP02TQ2N9B02D	2.9				12.3		
	LQP02TQ2N9B02L							
	LQP02TQ2N9C02D							
	LQP02TQ2N9C02L							
	LQP02TQ3N0B02D	3.0				12.2		
	LQP02TQ3N0B02L							
	LQP02TQ3N0C02D							
	LQP02TQ3N0C02L							
	LQP02TQ3N1B02D	3.1			0.9	12.0		290
	LQP02TQ3N1B02L							
	LQP02TQ3N1C02D							
	LQP02TQ3N1C02L							
	LQP02TQ3N2B02D	3.2				12.6		
	LQP02TQ3N2B02L							
	LQP02TQ3N2C02D							
	LQP02TQ3N2C02L							
	LQP02TQ3N3B02D	3.3				12.2		
	LQP02TQ3N3B02L							
	LQP02TQ3N3C02D							
	LQP02TQ3N3C02L							
	LQP02TQ3N4B02D	3.4			1.0	12.5	9.7	280
	LQP02TQ3N4B02L							
	LQP02TQ3N4C02D							
	LQP02TQ3N4C02L							
	LQP02TQ3N5B02D	3.5				12.1		
	LQP02TQ3N5B02L							
	LQP02TQ3N5C02D							
	LQP02TQ3N5C02L							
	LQP02TQ3N6B02D	3.6				11.5		
	LQP02TQ3N6B02L							
	LQP02TQ3N6C02D							
	LQP02TQ3N6C02L							
	LQP02TQ3N7B02D	3.7				11.4		270
	LQP02TQ3N7B02L							
	LQP02TQ3N7C02D							
	LQP02TQ3N7C02L							

Customer Part Number	MURATA Part Number	Inductance		Q (min)	DC Resistance (Ω max)	Self Resonant Frequency (GHz)		Rated Current (mA)
		(nH)	Tolerance			*Typ.	Min.	
	LQP02TQ3N8B02D	3.8	B:±0.1nH C:±0.2nH	10	1.0	11.1	9.7	270
	LQP02TQ3N8B02L							
	LQP02TQ3N8C02D							
	LQP02TQ3N8C02L							
	LQP02TQ3N9B02D	3.9				10.7	9.0	
	LQP02TQ3N9B02L							
	LQP02TQ3N9C02D							
	LQP02TQ3N9C02L							
	LQP02TQ4N0B02D	4.0				10.5		
	LQP02TQ4N0B02L							
	LQP02TQ4N0C02D							
	LQP02TQ4N0C02L							
	LQP02TQ4N1B02D	4.1				10.3		
	LQP02TQ4N1B02L							
	LQP02TQ4N1C02D							
	LQP02TQ4N1C02L							
	LQP02TQ4N2B02D	4.2				11.0		
	LQP02TQ4N2B02L							
	LQP02TQ4N2C02D							
	LQP02TQ4N2C02L							
	LQP02TQ4N3H02D	4.3	H:±3% J:±5%			10.8		
	LQP02TQ4N3H02L							
	LQP02TQ4N3J02D							
	LQP02TQ4N3J02L							
	LQP02TQ4N7H02D	4.7				9.6	8.5	
	LQP02TQ4N7H02L							
	LQP02TQ4N7J02D							
	LQP02TQ4N7J02L							
	LQP02TQ5N1H02D	5.1			1.2	9.2	7.8	250
	LQP02TQ5N1H02L							
	LQP02TQ5N1J02D							
	LQP02TQ5N1J02L							
	LQP02TQ5N6H02D	5.6			1.3	9.4		230
	LQP02TQ5N6H02L							
	LQP02TQ5N6J02D							
	LQP02TQ5N6J02L							
	LQP02TQ6N2H02D	6.2				8.5	7.2	220
	LQP02TQ6N2H02L							
	LQP02TQ6N2J02D							
	LQP02TQ6N2J02L							
	LQP02TQ6N8H02D	6.8			1.4	7.8	6.6	210
	LQP02TQ6N8H02L							
	LQP02TQ6N8J02D							
	LQP02TQ6N8J02L							
	LQP02TQ7N5H02D	7.5			1.5	8.1		200
	LQP02TQ7N5H02L							
	LQP02TQ7N5J02D							
	LQP02TQ7N5J02L							
	LQP02TQ8N2H02D	8.2			1.6	7.8		190
	LQP02TQ8N2H02L							
	LQP02TQ8N2J02D							
	LQP02TQ8N2J02L							

Customer Part Number	MURATA Part Number	Inductance		Q (min)	DC Resistance (Ω max)	Self Resonant Frequency (GHz)		Rated Current (mA)
		(nH)	Tolerance			*Typ.	Min.	
	LQP02TQ9N1H02D	9.1	H:±3% J:±5%	10	1.7	7.0	5.9	170
	LQP02TQ9N1H02L							
	LQP02TQ9N1J02D							
	LQP02TQ9N1J02L							
	LQP02TQ10NH02D	10				6.5	5.5	
	LQP02TQ10NH02L							
	LQP02TQ10NJ02D							
	LQP02TQ10NJ02L							
	LQP02TQ11NH02D	11			1.9	5.9	3.5	140
	LQP02TQ11NH02L							
	LQP02TQ11NJ02D							
	LQP02TQ11NJ02L							
	LQP02TQ12NH02D	12			2.1	5.7		
	LQP02TQ12NH02L							
	LQP02TQ12NJ02D							
	LQP02TQ12NJ02L							
	LQP02TQ13NH02D	13				5.6	3.0	
	LQP02TQ13NH02L							
	LQP02TQ13NJ02D							
	LQP02TQ13NJ02L							
	LQP02TQ14NH02D	14			2.3	5.1		
	LQP02TQ14NH02L							
	LQP02TQ14NJ02D							
	LQP02TQ14NJ02L							
	LQP02TQ15NH02D	15						
	LQP02TQ15NH02L							
	LQP02TQ15NJ02D							
	LQP02TQ15NJ02L							
	LQP02TQ16NH02D	16			2.5	4.9	2.5	
	LQP02TQ16NH02L							
	LQP02TQ16NJ02D							
	LQP02TQ16NJ02L							
	LQP02TQ17NH02D	17				4.7		
	LQP02TQ17NH02L							
	LQP02TQ17NJ02D							
	LQP02TQ17NJ02L							
	LQP02TQ18NH02D	18		8				
	LQP02TQ18NH02L							
	LQP02TQ18NJ02D							
	LQP02TQ18NJ02L							
	LQP02TQ19NH02D	19			2.9	4.4	2.7	
	LQP02TQ19NH02L							
	LQP02TQ19NJ02D							
	LQP02TQ19NJ02L							
	LQP02TQ20NH02D	20						
	LQP02TQ20NH02L							
	LQP02TQ20NJ02D							
	LQP02TQ20NJ02L							
	LQP02TQ21NH02D	21			3.2		2.3	120
	LQP02TQ21NH02L							
	LQP02TQ21NJ02D							
	LQP02TQ21NJ02L							
	LQP02TQ22NH02D	22						
	LQP02TQ22NH02L							
	LQP02TQ22NJ02D							
	LQP02TQ22NJ02L							

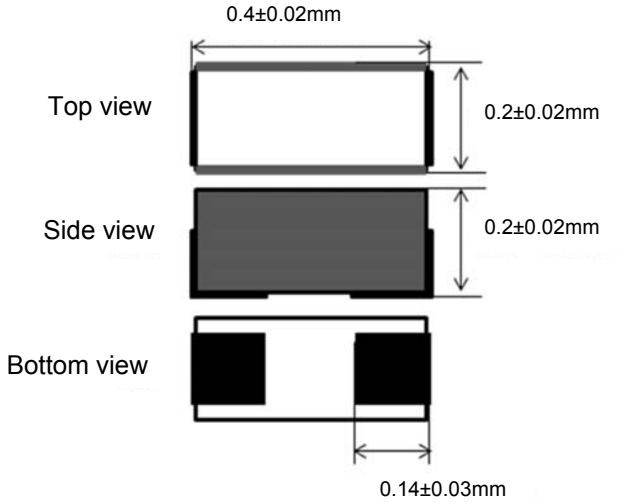
* Typical value is actual performance.

4. Testing Conditions

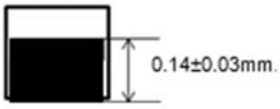
《Unless otherwise specified》
Temperature : Ordinary Temperature / 15°C to 35°C
Humidity: Ordinary Humidity / 25%(RH) to 85 %(RH)

《In case of doubt》
Temperature : 20°C ± 2°C
Humidity : 60%(RH) to 70 %(RH)
Atmospheric Pressure : 86kPa to 106 kPa

5. Appearance and Dimensions



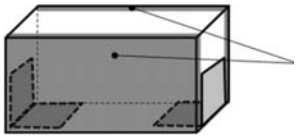
End view



■Unit Mass (Typical value)
0.05mg

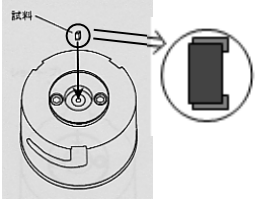
6. Marking

Side surface identification marking :Blue



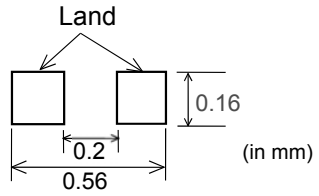
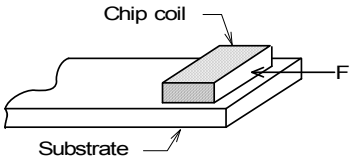
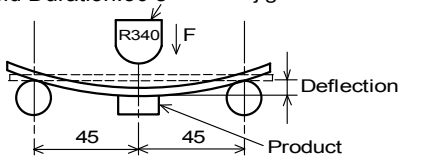
Both side surface
Blue

7.Electrical Performance

No.	Item	Specification	Test Method
7.1	Inductance	Inductance shall meet item 3.	Measuring Equipment: KEYSIGHT E4991A or equivalent Measuring Frequency:500MHz Measuring Condition: Test signal level / about 0dBm Electrical length / 27.3mm Measuring Fixture: KEYSIGHT 16196D Insert Chip coil in the hole in order that the polarity marking is at the top of the side surface. Contact coil with each terminal by adding the weigh cover. See diagram below.  Chip coil placement hole: ϕ0.3mm Measuring Method:See the endnote. <Electrical Performance:Measuring Method of Inductance/Q>
7.2	Q	Q shall meet item 3.	

No.	Item	Specification	Test Method
7.3	DC Resistance	DC Resistance shall meet item 3.	Measuring Equipment:Digital multi meter
7.4	Self Resonant Frequency(S.R.F)	S.R.F shall meet item 3.	Measuring Equipment: KEYSIGHT N5230A or equivalent
7.5	Rated Current	Self temperature rise shall be limited to 25°C max.	The rated current is applied.

8.Mechanical Performance

No.	Item	Specification	Test Method
8.1	Shear Test	Chip coil shall not be damaged after tested as test method.	Substrate:Glass-epoxy substrate  Force:1N Hold Duration:5 s±1 s Applied Direction: Parallel to PCB. 
8.2	Bending Test	Chip coil shall not be damaged after tested as test method.	Substrate:Glass-epoxy substrate (100mm × 40mm × 0.8mm) Speed of Applying Force:1mm /s Deflection:1mm Hold Duration:30 s 
8.3	Vibration	Appearance:No damage Inductance Change: within ±10%	Substrate:Glass-epoxy substrate Oscillation Frequency: 10Hz to 2000Hz to 10Hz for 20 min Total amplitude 1.5 mm or Acceleration amplitude 196 m/s^2 whichever is smaller. Testing Time:A period of 2h in each of 3 mutually perpendicular directions.
8.4	Solderability	The electrode shall be at least 90% covered with new solder coating.	Flux: Ethanol solution of rosin 25(wt)% (Immersed for 5s to 10s) Solder:Sn-3.0Ag-0.5Cu Pre-Heating:150°C±10°C / 60s to 90s Solder Temperature:240°C±5°C Immersion Time:3s±1s
8.5	Resistance to Soldering Heat	Appearance:No damage Inductance Change: within ±10%	Flux: Ethanol solution of rosin 25(wt)% (Immersed for 5s to 10s) Solder:Sn-3.0Ag-0.5Cu Pre-Heating:150°C±10°C / 60s to 90s Solder Temperature:260°C±5°C Immersion Time:5s±1s Then measured after exposure in the room condition for 24h±2h.

9.Environmental Performance

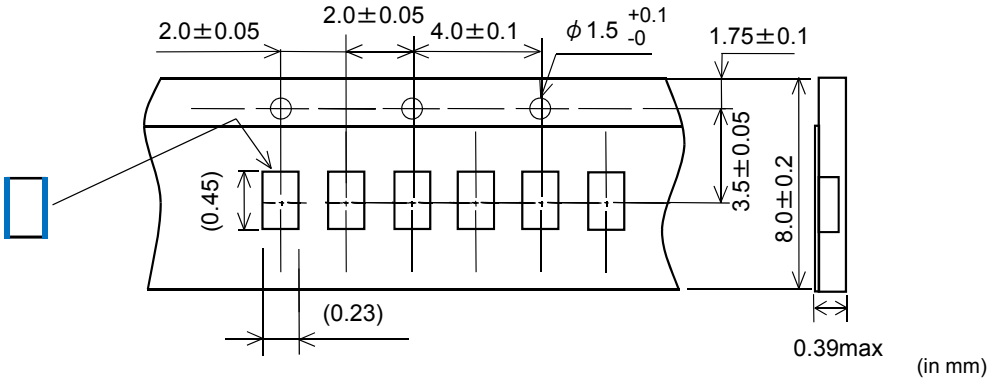
It shall be soldered on the substrate.

No.	Item	Specification	Test Method
9.1	Heat Resistance	Appearance:No damage Inductance Change: within ±10%	Substrate:Glass-epoxy substrate Temperature:125°C±2°C Time:1000h (+48h,-0h) Then measured after exposure in the room condition for 24h±2h.
9.2	Cold Resistance		Substrate:Glass-epoxy substrate Temperature:-55°C±3°C Time:1000 h (+48h,-0h) Then measured after exposure in the room condition for 24h±2h.
9.3	Humidity		Substrate:Glass-epoxy substrate Temperature:40°C±2°C Humidity:90%(RH) to 95%(RH) Time:1000 h(+48h,-0h) Then measured after exposure in the room condition for 24h±2h.
9.4	Temperature Cycle		Substrate:Glass-epoxy substrate 1 cycle: 1 step:-55°C±2°C / 30min±3 min 2 step:Ordinary temp. / 10~15 min 3 step:125°C±2°C / 30±3 min 4 step: Ordinary temp. / 10~15 min Total of 10 cycles Then measured after exposure in the room condition for 24h±2h.

10.Specification of Packaging

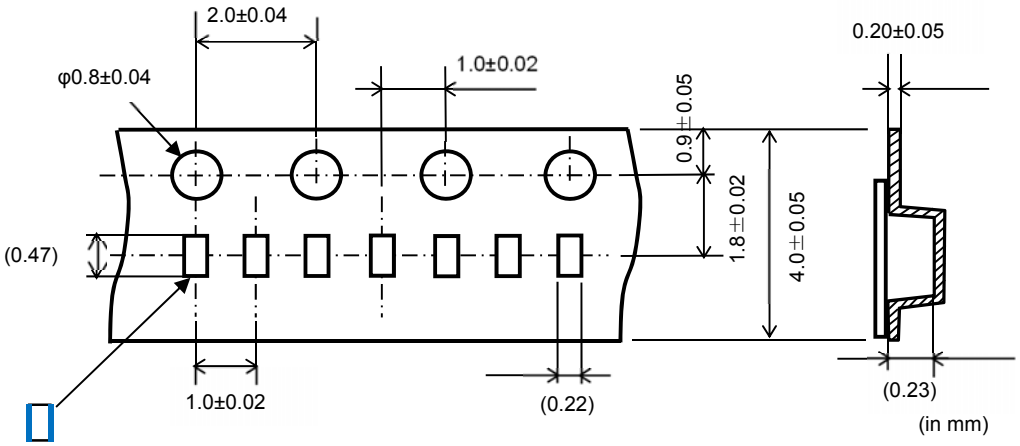
10.1 Appearance and Dimensions of paper tape

【8mm-wide / paper tape】



(in mm)

【4mm-wide / plastic tape】



Dimension of the Cavity is measured at the bottom side.

10.2 Specification of Taping

【8mm-wide / paper tape】

(1) Packing quantity (standard quantity)
20,000 pcs. / reel

(2) Packing Method
Products shall be packed in the cavity of the base tape and sealed by cover tape.

(3) Sprocket hole
The sprocket holes are to the right as the tape is pulled toward the user.

(4) Spliced point
Base tape and Cover tape has no spliced point.

(5) Missing components number
Missing components number within 0.1 % of the number per reel or 1 pc. , whichever is greater, and are not continuous. The Specified quantity per reel is kept.

【4mm-wide / plastic tape】

(1) Packing quantity (standard quantity)
40,000 pcs. / reel

(2) Packing Method
Products shall be packed in the each embossed cavity of plastic tape and sealed by cover tape.

(3) Sprocket hole
Sprocket hole shall be located on the left-hand side toward the direction of feed.

(4) Spliced point
Plastic tape and Cover tape has no spliced point.

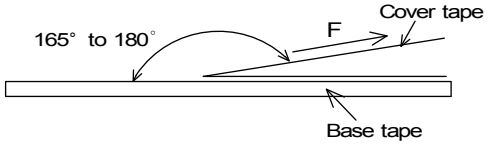
(5) Missing components number
Missing components number within 0.1 % of the number per reel or 1 pc. , whichever is greater, and are not continuous. The Specified quantity per reel is kept.

10.3 Pull Strength

Cover tape	5N min

10.4 Peeling off force of cover tape

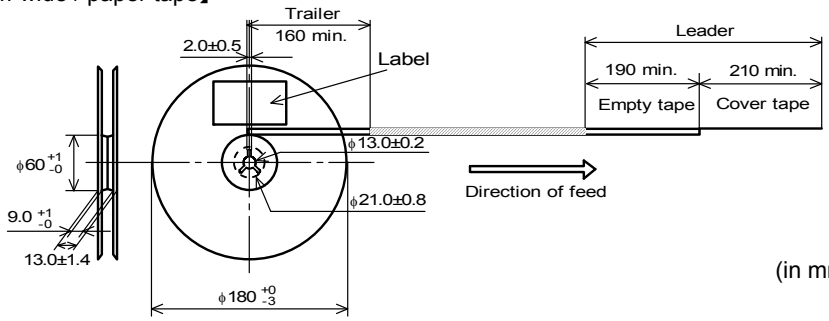
Speed of Peeling off	300mm/min
Peeling off force	0.1N to 0.6N (minimum value is typical)



10.5 Dimensions of Leader-tape, Trailer and Reel

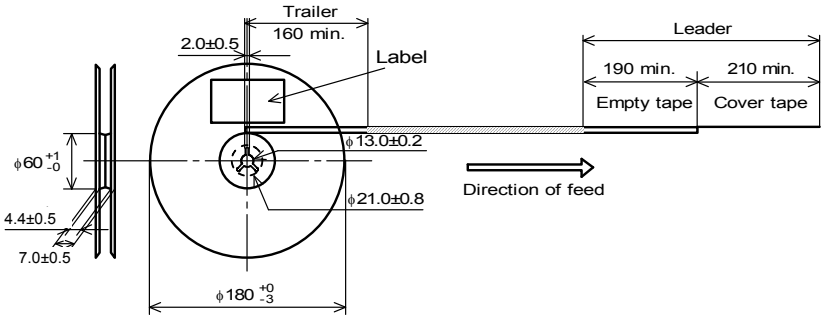
There shall be leader-tape (top tape and empty tape) and trailer-tape (empty tape) as follows.

【8mm-wide / paper tape】



(in mm)

【4mm-wide / plastic tape】



10.6 Marking for reel

Customer part number, MURATA part number, Inspection number(∗1) ,RoHS Marking(∗2), Quantity etc ・・・

∗1) <Expression of Inspection No.> □□ OOOO ×××
(1) (2) (3)

(1) Factory Code
(2) Date First digit : Year / Last digit of year
Second digit : Month / Jan. to Sep. → 1 to 9, Oct. to Dec. → O,N,D
Third, Fourth digit : Day
(3) Serial No.

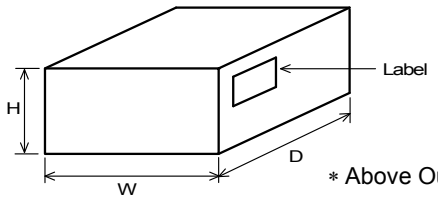
∗2) <Expression of RoHS Marking > ROHS – Y (△)
(1) (2)

(1) RoHS regulation conformity parts.
(2) MURATA classification number

10.7 Marking for Outside package (corrugated paper box)

Customer name, Purchasing order number, Customer part number, MURATA part number, RoHS Marking (∗2) ,Quantity, etc ・・・

10.8 Specification of Outer Case



Outer Case Dimensions (mm)			Standard Reel Quantity in Outer Case (Reel)
W	D	H	
186	186	93	5(8mm-wide / paper tape)
			10(4mm-wide / plastic tape)

∗ Above Outer Case size is typical. It depends on a quantity of an order.

11. ⚠ Caution

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

(1) Aircraft equipment
(2) Aerospace equipment
(3) Undersea equipment
(4) Power plant control equipment
(5) Medical equipment
(6) Transportation equipment (vehicles, trains, ships, etc.)
(7) Traffic signal equipment
(8) Disaster prevention / crime prevention equipment
(9) Data-processing equipment
(10) Applications of similar complexity and /or reliability requirements to the applications listed in the above

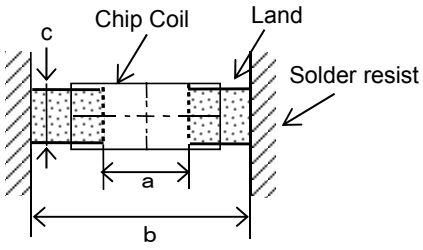
12. Notice

Products can only be soldered with reflow.

This product is designed for solder mounting.

Please consult us in advance for applying other mounting method such as conductive adhesive.

12.1 Land pattern designing



a	0.20
b	0.56
c	0.16

(in mm)

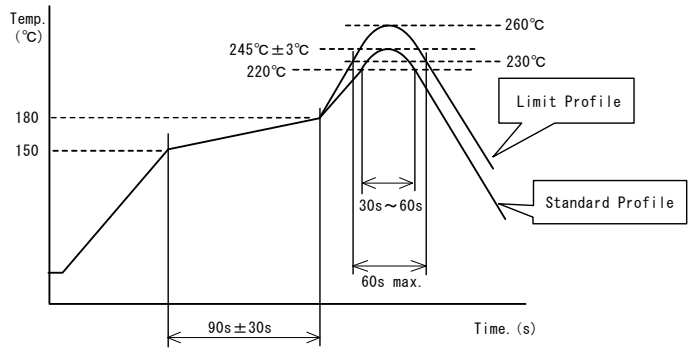
12.2 Flux, Solder

- Use rosin-based flux.
  Don't use highly acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).
  Don't use water-soluble flux.
- Use Sn-3.0Ag-0.5Cu solder.
- Standard thickness of solder paste : 50 μm to 65 μm.

12.3 Reflow soldering conditions

- Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150°C max. Cooling into solvent after soldering also should be in such a way that the temperature difference is limited to 100°C max.
  Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of products quality.
- Standard soldering profile and the limit soldering profile is as follows.
  The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.

・Reflow soldering profile



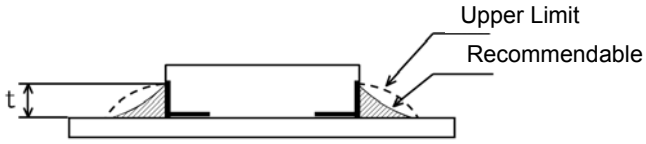
	Standard Profile	Limit Profile
Pre-heating	150°C～180°C 、90s±30s	
Heating	above 220°C、30s～60s	above 230°C、60s max.
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times

12.4 Reworking with soldering iron

Reworking with soldering iron is disapproved.

12.5 Solder Volume

・ Solder shall be used not to be exceeded the upper limits as shown below.



1/3T≦t≦T
T : thickness of product

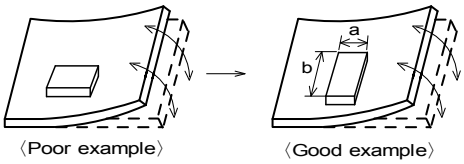
Accordingly increasing the solder volume, the mechanical stress to Chip is also increased.
Exceeding solder volume may cause the failure of mechanical or electrical performance.

12.6 Attention regarding P.C.B. bending

The following shall be considered when designing and laying out P.C.B.'s.

(1) P.C.B. shall be designed so that products are not subject to the mechanical stress due to warping the board.

[Products direction]



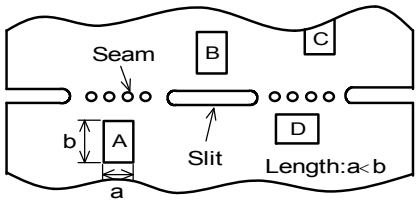
Products shall be located in the sideways direction (Length:a＜b) to the mechanical stress.

(2) Components location on P.C.B. separation.

It is effective to implement the following measures, to reduce stress in separating the board.
It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

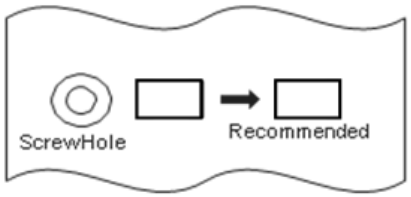
Contents of Measures	Stress Level
(1) Turn the mounting direction of the component parallel to the board separation surface.	A > D *1
(2) Add slits in the board separation part.	A > B
(3) Keep the mounting position of the component away from the board separation surface.	A > C

*1 A > D is valid when stress is added vertically to the perforation as with Hand Separation.
If a Cutting Disc is used, stress will be diagonal to the PCB, therefore A > D is invalid.



(3) Mounting Components Near Screw Holes

When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw. Mount the capacitor in a position as far away from the screw holes as possible.



12.7 Cleaning Conditions

Products shall be cleaned on the following conditions.

(1) Cleaning temperature shall be limited to 60°C max.(40°C max for IPA)
(2) Ultrasonic cleaning shall comply with the following conditions with avoiding the resonance phenomenon at the mounted products and P.C.B.
Power : 20 W / l max. Frequency : 28kHz to 40kHz Time : 5 min max.
(3) Cleaner
1. Alcohol type cleaner
Isopropyl alcohol (IPA)
2. Aqueous agent
PINE ALPHA ST-100S
(4) There shall be no residual flux and residual cleaner after cleaning.
In the case of using aqueous agent, products shall be dried completely after rinse with de-ionized water in order to remove the cleaner.
(5) Other cleaning Please contact us.

12.8 Resin coating

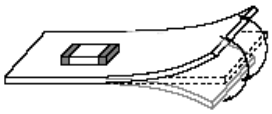
When products are coated with resin, please contact us in advance.

12.9 Handling of a substrate

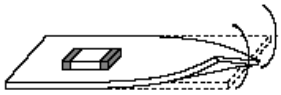
(1)There is a possibility of chip cracking caused by PCB expansion/contraction with heat, because stress on a chip is different depending on PCB material and structure.
When the thermal expansion coefficient greatly differs between the board used for mounting and the chip, it will cause cracking of the chip due to the thermal expansion and contraction.
The chip is assumed to be mounted on the PCB of glass-epoxy material, and we don't test with other PCB material which has different thermal expansion coefficient from Glass-epoxy.
When other PCB materials are considered, please be sure to evaluate by yourself.

(2)After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.
Excessive mechanical stress may cause cracking in the product.
In case of the mounting on flexible PCB, there is a possibility of chip cracking caused by mechanical stress even from small bending or twisting.
When the flexible PCB is considered, please be sure to evaluate by yourself.

Bending



Twisting



12.10 Storage and Handing Requirements

(1) Storage period
Use the products within 12 months after deliverd.
Solderability should be checked if this period is exceeded.

(2) Storage conditions
・Products should be stored in the warehouse on the following conditions.
Temperature : -10°C ~ 40°C
Humidity : 15% to 85% relative humidity No rapid change on temperature and humidity.
・Products should not be stored on bulk packaging condition to prevent the chipping of the core and the breaking of winding wire caused by the collision between the products.
・Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
・Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.

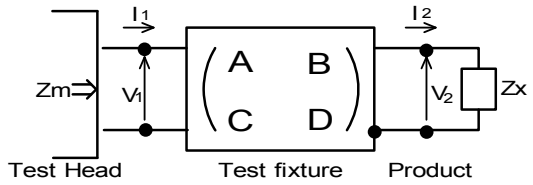
(3) Handling Condition
Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

13.⚠ Note

(1)Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
(2)You are requested not to use our product deviating from the reference specifications.
(3)The contents of this reference specification are subject to change without advance notice.
Please approve our product specifications or transact the approval sheet for product specifications before ordering

<Electrical Performance:Measuring Method of Inductance/Q>

(1) Residual elements and stray elements of test fixture can be described by F-parameter shown in following.



$$\begin{pmatrix} V_1 \\ I_1 \end{pmatrix} = \begin{pmatrix} A & B \\ C & D \end{pmatrix} \begin{pmatrix} V_2 \\ I_2 \end{pmatrix}$$

(2) The impedance of chip coil Zx and measured value Zm can be described by input/output current/voltage.

$$Zm=\frac{V_1}{I_1} \quad , \quad Zx=\frac{V_2}{I_2}$$

(3) Thus,the relation between Zx and Zm is following;

$$Zx=\alpha\frac{Zm-\beta}{1-Zm\,\Gamma}$$

where, α= D / A =1
β= B / D =Zsm-(1-Yom Zsm)Zss
Γ= C / A =Yom

(Zsm:measured impedance of short chip
Zss:residual impedance of short chip (0.110nH)
Yom:measured admittance when opening the fixture)

(4) Lx and Qx shall be calculated with the following equation.

$$Lx=\frac{Im(Zx)}{2\pi f} \quad , \quad Qx=\frac{Im(Zx)}{Re(Zx)}$$

Lx :Inductance of chip coil
Qx:Q of chip coil
f :Measuring frequency